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# Design-Process-Technology Co-optimization for Manufacturability XIII

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## Contents

- vii Authors
- ix Conference Committee

#### **DESIGN-TECHNOLOGY CO-OPTIMIZATION**

- 10962 03 Optimization of read and write performance of SRAMs for node 5nm and beyond [10962-2]
- 10962 05 Backside power delivery as a scaling knob for future systems [10962-4]
- 10962 06 CFET standard-cell design down to 3Track height for node 3nm and below [10962-5]

#### LAYOUT ANALYTICS

- 10962 07 Persistent homology analysis of complex high-dimensional layout configurations for IC physical designs [10962-6]
- 10962 08 Machine learning based wafer defect detection [10962-7]
- 10962 0A Fast detection of largest repeating layout pattern [10962-9]
- 10962 OB **Process window-based feature and die failure rate prediction** [10962-10]

#### MACHINE LEARNING

10962 0D	Optical proximity correction using bidirectional recurrent neural network (BRNN) [10962-12]
10962 OE	Investigation of machine learning for dual OPC and assist feature printing optimization [10962-13]
	PROCESS MODELING AND LAYOUT OPTIMIZATION

10962 0H **3D resist reflow compact model for imagers microlens shape optimization** [10962-16]

- 10962 01 Efficient electrical characteristics estimation techniques for sub 20 nm FDSOI integrated circuits with non-rectangular gate patterning effects [10962-17]
- 10962 0J Optimizing DFM scores by using a genetic evolution algorithm [10962-18]
- 10962 OK Full-chip layout optimization for photo process window improvement of 3D NAND metal routing level [10962-19]

#### DESIGN INTERACTIONS WITH METROLOGY: JOINT SESSION WITH CONFERENCES 10959 AND 10962

10962 0L Critical defect detection, monitoring and fix through process integration engineering by using D2DB pattern monitor solution [10962-20]

#### EUV OPC AND MODELING: JOINT SESSION WITH CONFERENCES 10957 AND 10962

10962 ON SAQP spacer merge and EUV self-aligned block decomposition at 28nm metal pitch on imec 7nm node [10962-22]

#### HOTSPOT DETECTION

- 10962 0Q Lithography hotspot candidate detection using coherence map (Invited Paper) [10962-25]
- 10962 OR CAPP: context analyzer and printability predictor [10962-26]
- 10962 0S Hotspot detection using squish-net [10962-27]
- 10962 0T Multi-criteria hotspot detection using pattern classification [10962-28]
- 10962 0U Multilayer CMP hotspot modeling through deep learning [10962-29]

#### POSTER SESSION

10962 OV	SALELE process from theory to fabrication [10962-30]
10962 OX	Sample patterns extraction from layout automatically based on hierarchical cluster algorithm for lithography process optimization [10962-32]
10962 OY	Incorporating process variation contours in design rule calculation and SRAM design optimization [10962-33]

10962 10	Copper interconnect topography simulation in 3D NAND designs [10962-35]
10962 11	FEOL CMP modeling challenges and solution in 3D NAND [10962-36]
10962 12	Design rule exploration for width sensitive zone for metal layers in advanced nodes [10962-37]
10962 13	Experimental study of the strong halation-effect of a fully PGMEA-based under-layer on a highly etched topography in the dual damascene via-first approach [10962-38]
10962 14	An efficient way of automatic layout decomposition and pattern classification [10962-39]
10962 15	A smart litho friendly design method to enable fast lithography hotspots detection in design flow [10962-40]
10962 16	Machine learning to improve accuracy of fast lithographic hotspot detection [10962-41]
10962 17	Novel pattern-centric solution for high performance 3D NAND VIA dishing metrology [10962-42]

### Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abdulghany, Ahmed, 0G Adam, Kostas, OB Allouti, Nacima, OH Bakshi, Janam, OG, OJ Bérard-Bergery, Sébastien, OH Bevlier, Charlotte, OH Beyne, Eric, 05 Blackwell, Don, 0G Brooker, Peter, OE Burbine, Andre, OB Cai, Jia-Syun, Ol Cantú, Pietro, 13 Capodieci, Luigi, 07 Chae, J. K., 06 Chava, Bharani, 05 Chen, Guojie, 0L Chen, Jingsong, 0A Chen, Rui, 12 Chen, Ying, 0X Chen, Yulu, 0E Cheng, Guojie, 17 Chien, Sheng-Wei, Ol Choi, Soo Han, ON Christensen, Eric, OK Clifford, Chris, OB Cordeau, Maryline, OH Corneo, Nicoletta, 13 Dai, Vito, 07 Dall'Asta, Valentina, 13 Debacker, P., 06 Digaum, Jennefir L., OK Dong, Lisong, 0X, 12 Dounde, A., 06 Drissi, Youssef, OV Du, Chunshan, 10, 11, 12, 14, 15 Eleouet, Raphaël, OH ElGhoroury, Ahmed, 16 ElManhawy, Wael, 16 Elsemary, Ahmed Mounir, OJ Fan, Luming, 10, 11 Fenger, Germain, 0V Francisco, Luis, OU Gai, Tianyang, OX Gao, Pengzheng, OX Gao, Shao Wen, 08 Gennari, Frank, OS Ghulghazaryan, Ruben, 10, 11 Gillijns, Werner, OV Guajardo, Marco, OE

Guan, Tiapeng, OL Guissi, Sofiane, 05 Gupta, Mohit, 03 Hamed-Fatehy, Ahmed, 0V Hazart, Jérôme, OH Henry, Jean-Baptiste, OH Hermann, Thomas, 0G Hong, Le, 08 Hooker, Kevin, OE Hu, Wei, OL Hu, Xinyi, 10, 11, 14, 15 Huda, Rais, 0G Islam, Moydul, OK Ismail, Mohamed, OJ Jiang, Peng, 10, 11 Jourdain, Anne, 05 Jung, Sangwoo, 16 Kabeel, Aliaa, 16 Kan, Huan, 14 Kang, Jae-hyun, 16 Katakamsetty, Ushasree, OU Katzman, Gail, 0G Kim, Hung-Eil, OK Kim, NamJae, 16 Kim, Ryan Ryoung Han, 06, 0N, 0V Kim, Young Chang, OB Kimura, Taiki, OQ, OT Kotani, Toshiya, OT Kotb, Rehab, OV Kureh, Yacoub, 07 Kwan, Joe, 16 Kwon, Yonghwi, 0D Kvu, J., 06 Lai, Ya-Chieh, OS Latinwo, Folarin, OE Lee, Chien-Lin, Ol Lee, Jae Uk, ON, OV Lee, Sangah, 16 Lee, Zhao Chuan, OG, OR Leng, Jianghua, OL Li, Rick, 10, 11 Li, Yang, 10, 11 Li, Yongfu, 0G, 0R Liao, Wenkui, OL Litterio, Emma, 13 Liu, Jinning, OY Liu, Limei, 14 Liu, Pan, 17

Liu, Yanxiang, 15

Liu, Zhengfang, 10, 11, 14, 15 Lucas, Kevin, OE Ma, Xiaolona, 15 Ma, Yuansheng, 08 Madhavan, Sriram, OG Madkour, Kareem, 16 Malik, Shobhit, OR Mao, Rui, OU Matsunawa, Tetsuaki, OQ, OT Matti, L., 06 McKay, Thomas, 0G Mehrotra, Vikas, 0G Mellmann, Joerg, 08 Mi, Jian, 17 Mocuta, Anda, 05, 06 Nojima, Shigeki, OQ, OT Oh, Jiwon, 16 Ong, Jonathan, OR Ostrovsky, Alain, OH Pack, Robert, OU Paek, Seung Weon, 16 Park, Kiheung, 16 Pathak, Piyush, OS Perez, Valerio, OR Quéméré, Patrick, OH Rabie, Asmaa, 16 Rousset, Valérie, OH Ryckaert, Julien, 05, 06 Ryoung han Kim, Ryan, OV Sanchez, Hamilton, OK Schroeder, Uwe Paul, OG, OJ Sejpal, Rajiv Naresh, OV Sha, Jing, OY Shafee, Marwa, 16 Shaik, Khaja Ahmad, 03, 05 Shalabi, Ahmed, OJ Shang, Shumay, OB Shao, Dongbing, OY Sherazi, S. M. Y., 06, 0N Shiely, James, OA Shin, Youngsoo, OD Shiozawa, Kazufumi, OT Simcoe, Michael, 0G Singh, Sonal, 08 Song, Youngsoo, 0D Spessot, Alessio, 03, 05, 06 Sturtevant, John, OB Su, Xiaojing, OX, 12 Su, Yajuan, OX, 12 Sun, Yuyang, 08 Tian, Ming, OL Tomaso, Florian, OH Tripathi, Vikas, OR Tsai, Kuen-Yu, Ol Tseng, I-Lun, OR Van Der Plaas, Geert, 05 Venkatachalam, Panneerselvam, 08 Verkest, D., 06 Verma, Piyush, OU Vikram, Abhishek, 0L, 17

Wan, Qijian, 10, 11, 14, 15 Wan, Zhenzhen, 14 Wang, Feng, 08 Wang, Guangyi, 10, 11 Wang, Hui, OL Wang, Lynn, 0G Wang, Sicong, 10, 11, 17 Weckx, Pieter, 03, 05 Wei, Yayi, OX, 12 Wong, Robert, OY Word, James, 08, 0V Wu, C.-E., 0E Xie, Qian, 08 Xu, Gao, 17 Yan, Lei, OL Yang, Haoyu, OS Ye, Tianchun, OX Yin, Lianghong, OB Young, Evangeline F.Y., 0A Yu, Bei, OS Zhang, Gary, OL Zhang, Liguo, 15 Zhang, Liming, 17 Zhang, Yu, OL Zhao, Baojun, OL Zheng, Aman, 10, 11 Zheng, Xin-Yang, Ol

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